

**Amendments to th Sp cification**

At page 1 before the “Technical Field” section, please insert the following:

**--RELATED PATENT DATA**

This patent resulted from a divisional application of U.S. Patent Application Serial No. 10/082,599, filed February 22, 2002, entitled “Interfacial Structure for Semiconductor Substrate Processing Chambers and Substrate Transfer Chambers and for Semiconductor Substrate Processing Chambers and Accessory Attachments, and Semiconductor Substrate Processor”, naming Craig M. Carpenter, Ross S. Dando, Allen P. Mardian, Kevin T. Hamer, Raynald B. Cantin, Philip H. Campbell, Kimberly R. Tscheopen and Randy W. Mercil as inventors, the disclosure of which is incorporated by reference.--

Please amend the paragraph beginning at line 22 of page 12 as follows:

In one aspect, the body, for example body 16, comprises a total volume at least a majority of which is a mass of material which is substantially non-metallic and thermally insulative. A sealant channel is received on the body peripheral of the substrate passageway. In one preferred embodiment, the sealant channel surrounds the passageway. In one preferred embodiment, the sealant channel is in the form of an O-ring groove, and in one embodiment, the sealant channel is received on the substantially metallic insert. In the depicted preferred embodiment, piece 44 of substantially metallic insert 40 depicts a sealant channel 72 peripherally surrounding passageway 55 (Figs. 4, 6 and 7). An o-ring, gasket or other sealing material would be received within channel 72, and another O-ring/gasket/sealant received relative to a channel formed in the transfer chamber flange for providing fluid tight seals between the interface blocks and the processing chamber and transfer chamber.